



## Material Content Data Sheet



<b>Sales Product Name</b>		BSO615C G		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000982388						
<b>Package</b>		PG-DSO-8-7		<b>Weight*</b>		81.34 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.490	3.06	3.06	30612	30612
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		114	
	non noble metal	zinc	7440-66-6	0.037	0.05		456	
	non noble metal	iron	7439-89-6	0.742	0.91		9118	
	non noble metal	copper	7440-50-8	30.114	37.02	37.99	370248	379936
wire	noble metal	gold	7440-57-5	0.432	0.53	0.53	5305	5305
encapsulation	organic material	carbon black	1333-86-4	0.226	0.28		2778	
	inorganic material	antimonytrioxide	1309-64-4	0.904	1.11		11112	
	plastics	brominated resin	-	0.904	1.11		11112	
	plastics	epoxy resin	-	5.197	6.39		63895	
	inorganic material	silicondioxide	60676-86-0	37.960	46.67	55.56	466710	555607
leadfinish	non noble metal	tin	7440-31-5	0.814	1.00	1.00	10006	10006
plating	noble metal	silver	7440-22-4	0.541	0.67	0.67	6656	6656
glue	plastics	epoxy resin	-	0.169	0.21		2079	
	noble metal	silver	7440-22-4	0.797	0.98	1.19	9799	11878
*deviation	< 10%					Sum in total:	100,00	1000000

### Important Remarks:

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